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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takashi SHOJI	07/10/2012
Takekazu SAKAI	07/10/2012

RECEIVING PARTY DATA

Name:	SHOWA DENKO K.K.
Street Address:	13-9, Shibadaimon 1-chome
City:	Minato-ku, Tokyo
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13522547

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: Q141289

Joanna Sanchez, New Apps Specialist

Total Attachments: 1

NAME OF SUBMITTER:

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PATENT REEL: 028573 FRAME: 0962 IOP \$40,00 13522547

ASSIGNMENT

Whereas, I/we, (1) Takashi SHOJI; and (2) Takekazu SAKAI of (1) to (2) c/o SHOWA DENKO K.K., 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 105-8518 Japan hereinafter called assignor(s), have invented ertain improvements in

APPARATUS FOR ADHERING SOLDER POWDER AND METHOD FOR ADHERING SOLDER POWDER TO ELECTRONIC CIRCUIT BOARD

and executed an application for Letters Patent of the United States of America therefor on

July 10, 2012; and

Whereas, SHOWA DENKO K.K. of 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 105-8518 Japan (assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America and all countries foreign thereto, including the rights of priority under the International Convention of Paris (1883) as amended, and I/we request the Director – U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we hereby agree that the assignee may apply for foreign Letters Patent on the invention and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

I/We hereby authorize and request my/our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3213 to insert here in parentheses (Application number 13/522,547 , filed July 17, 2012) the filing date and application number of said application when known.

Date: July 10, 2012

Date: July 10, 2012

Takekazu SAKAI

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

s Takekazu Dakar

PATENT REEL: 028573 FRAME: 0963

RECORDED: 07/18/2012